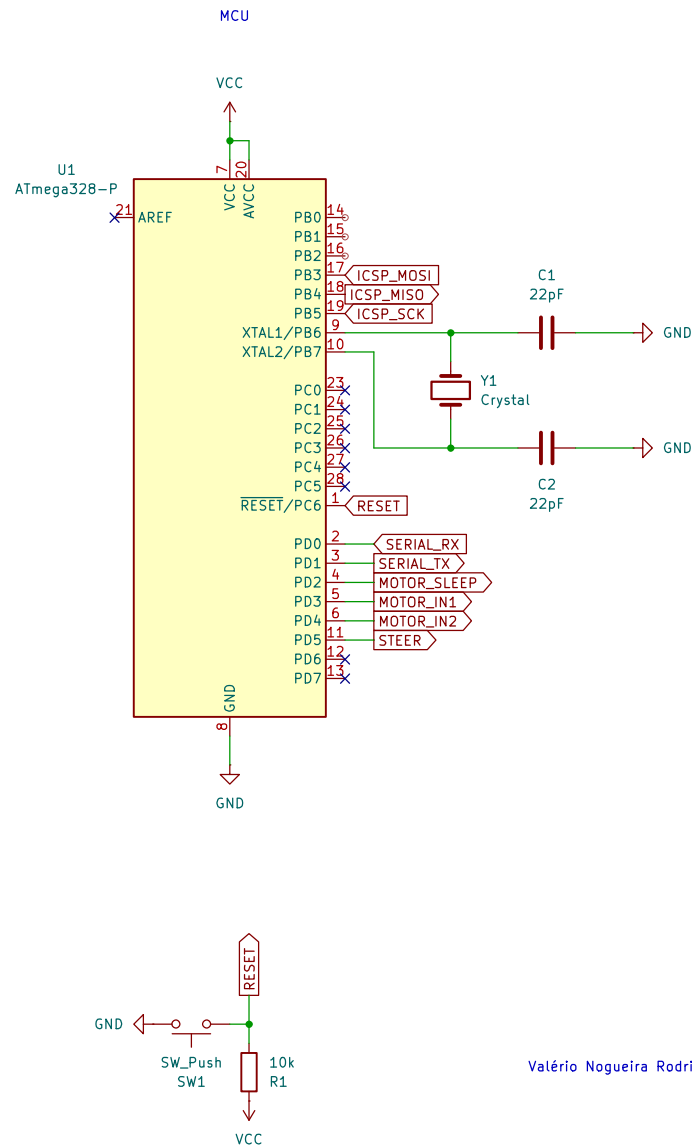
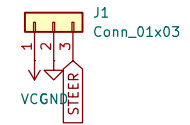


Low ESR ceramic capacitors should be utilized for the VM-to-GND and VCC-to-GND bypass capacitors. XSR and X7R types are recommended.

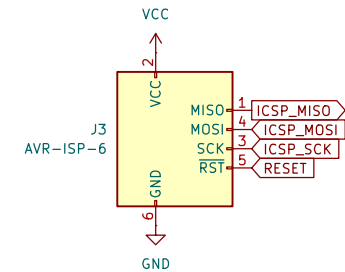
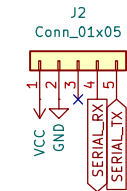
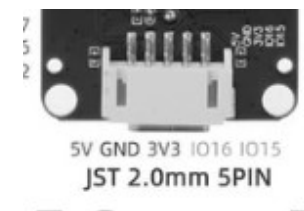
- The VM and VCC power supply capacitors should be placed as close to the device as possible to minimize the loop inductance.
- The VM power supply bulk capacitor can be of ceramic or electrolytic type, but should also be placed as close as possible to the device to minimize the loop inductance.
- VM, OUT1, OUT2, and GND carry the high current from the power supply to the outputs and back to ground. Thick metal routing should be utilized for these traces as is feasible.
- GND should connect directly on the PCB ground plane.
- The device thermal pad should be attached to the PCB top layer ground plane and internal ground plane (when available) through thermal vias to maximize the PCB heat sinking.
- The copper plane area attached to the thermal pad should be maximized to ensure optimal heat sinking.



Conector p/ sistema de direção



Conector p/ módulo de visão



Valério Nogueira Rodrigues Júnior